



PRODUCTS

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IT-180BS No Flow Prepreg

High Tg Multifunctional Epoxy Resin

IT-180 no/low flow prepreg is an advanced high Tg (165 °C by DSC) multifunctional epoxy with high thermal reliability and CAF resistance. It's designed for rigid flex board and heat sink bonding in 260 °C Lead free assembly.

Key Features =====

Advanced High Tg Resin Technology

Industrial standard material with high Tg (165 °C by DSC), excellent thermal reliability and CAF resistance providing long-term reliability for industrial and automobile application.

Lead-Free Assembly Compatible

RoHS compliant and suitable for high thermal reliability needs, and Lead free assemblies with a maximum reflow temperature of 260 °C.

Prepreg Availability

The glass styles of 1080, 1078, 1067 Prepreg are available that contain 20-120mil circular flow for different customer's designs and applications.

Applications

Rigid Flex Boards

Heat Sink Bonding

Cavity PCB Design

Industrial Approval

UL 94 V-0

RoHS Compliant

IT-180BS No Flow Prepreg

High Tg Multifunctional Filled Epoxy Resin

Properties

IT-180 NF Properties (Laminated Prepreg)	Typical Values	Units	Test Methods
			IPC-TM-650
Glass Transition Temperature (Tg)- DSC	165	°C	2.4.25 2.4.24
Decomposition Temperature (Td)	328	°C	2.4.24.6 (5% wt loss)
Permittivity (Dk) @ 1 MHz	3.9	---	2.5.5.9
Loss Tangent (Df) @ 1 MHz	0.024	---	2.5.5.9
Volume Resistivity, minimum C-96/ 35/ 90 After Moisture Resistance At Elevated Temperature: E- 24/ 125	3.0x10 ¹⁰ 3.0x10 ¹⁰ 5.0x10 ¹⁰	MΩ-cm	2.5.17.1
Surface Resistivity, minimum C-96/ 35/ 90 After Moisture Resistance At Elevated Temperature: E- 24/ 125	3.0x10 ¹⁰ 3.0x10 ¹⁰ 4.0x10 ¹⁰	MΩ	2.5.17.1
Electric Strength, minimum	45	kV/ mm	2.5.6.2
Arc Resistance, minimum	125	Sec	2.5.1
Dielectric Breakdown, minimum	60	kV	2.5.6
Peel Strength, As received- 1oz copper	8	lb/ in ²	2.4.8
Moisture Absorption, maximum	0.12	%	2.6.2.1
Flammability	V-0	Rating	UL 94

Data are based on 8 plies 1078 laminated prepreg

Prepreg Specifications

Glass Style	Resin Content (%)	Circular Flow (mil)	Pressed Thickness (mil)
1080	65+/-2	20-120	3.3+/-0.3
	63+/-2	20-120	3.1+/-0.3
1078	65+/-2	20-120	3.2+/-0.3
	63+/-2	20-120	3.0+/-0.3
1067	71.5+/-2	20-120	2.6+/-0.3
	65+/-2	20-120	2.2+/-0.3

The above data and fabrication guide provide designers and PCB shop for their reference. We believe that these information are accurate, however, the data may vary depend on the test methods and specification used. The actual sales of the product should be according to specification in the agreement between ITEQ and its customer. ITEQ reserves the right to revise its data at any time without notice and maintain the best information available to users.